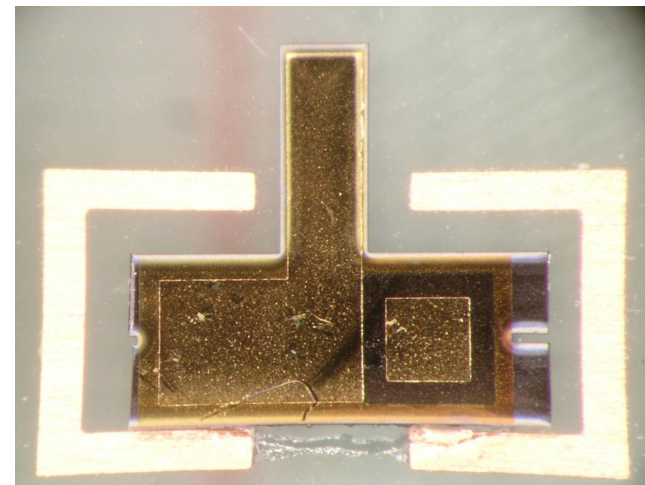
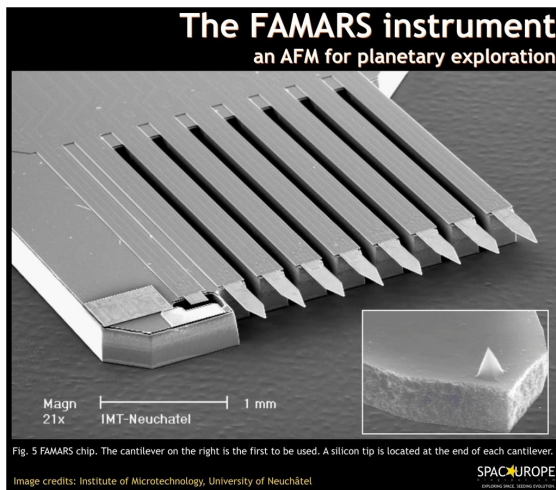
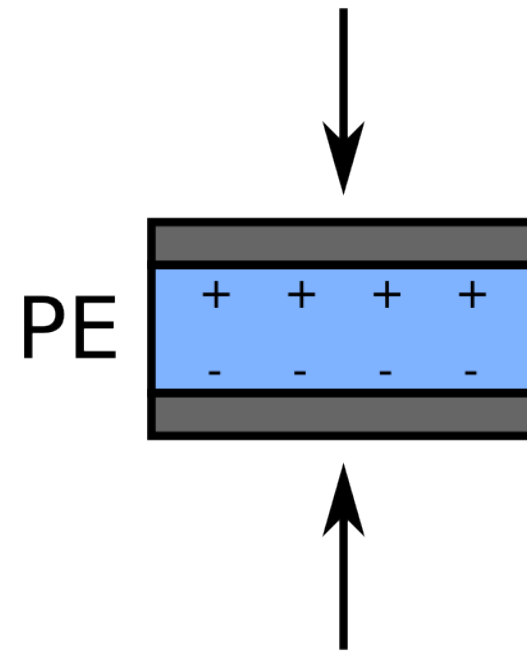
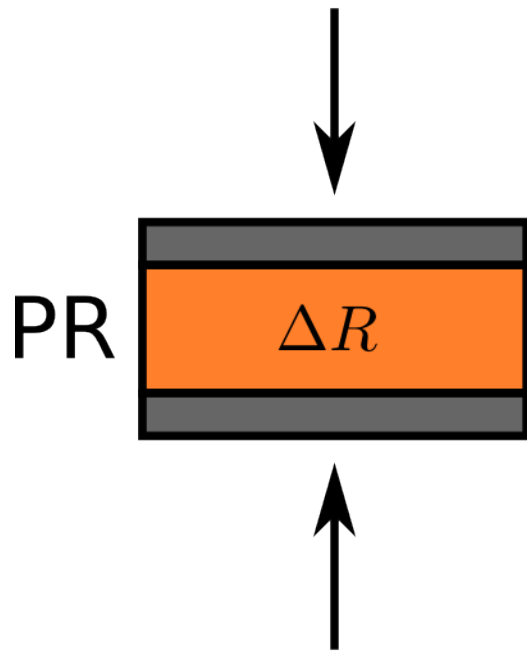


and Cantilever Thermal Design

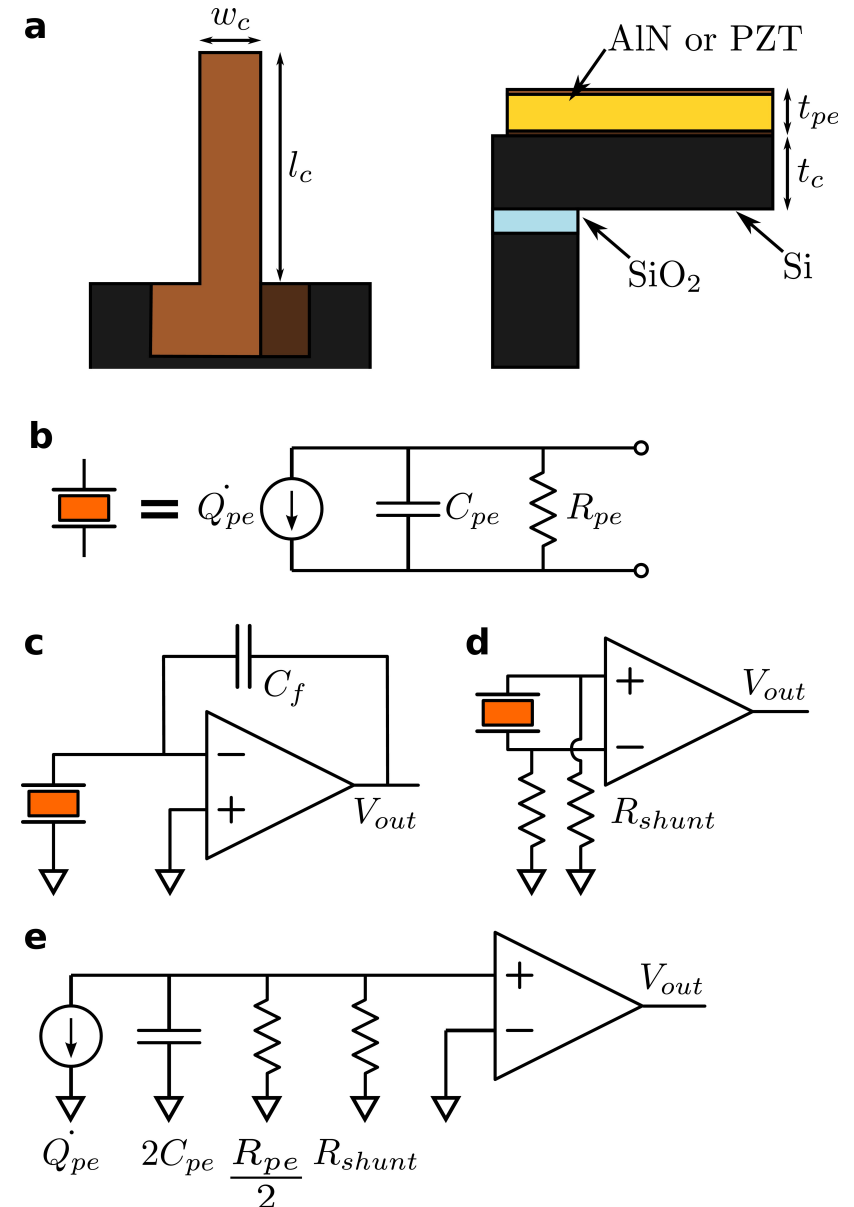
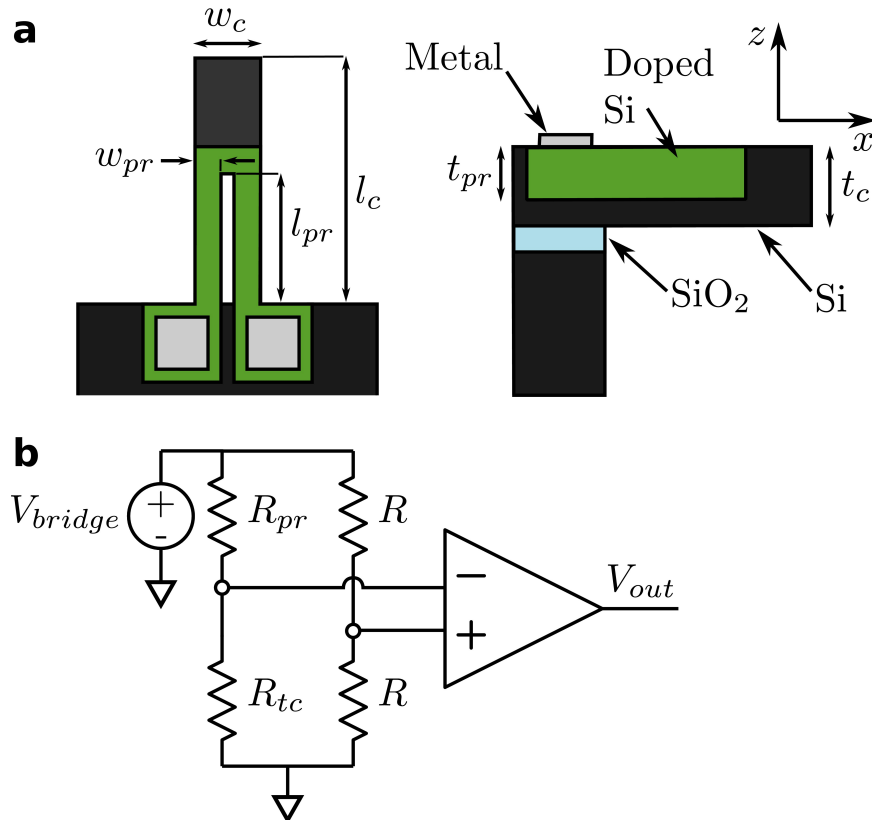
Joey Doll
4/30/2010

Piezoresistive (PR) vs. Piezoelectric (PE) Sensing

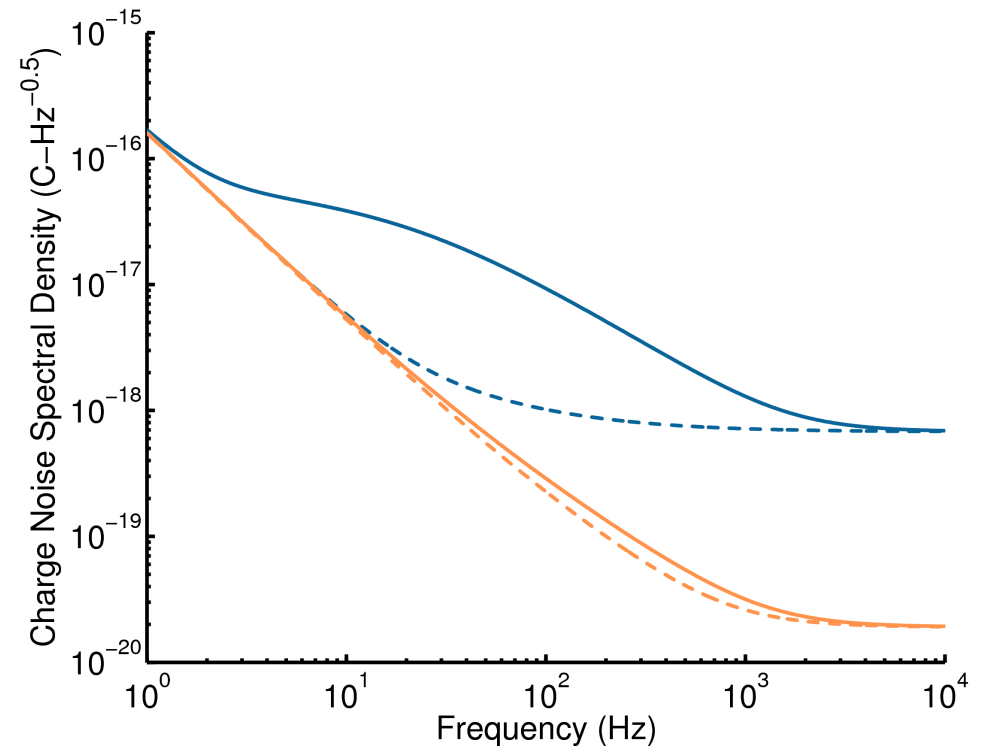
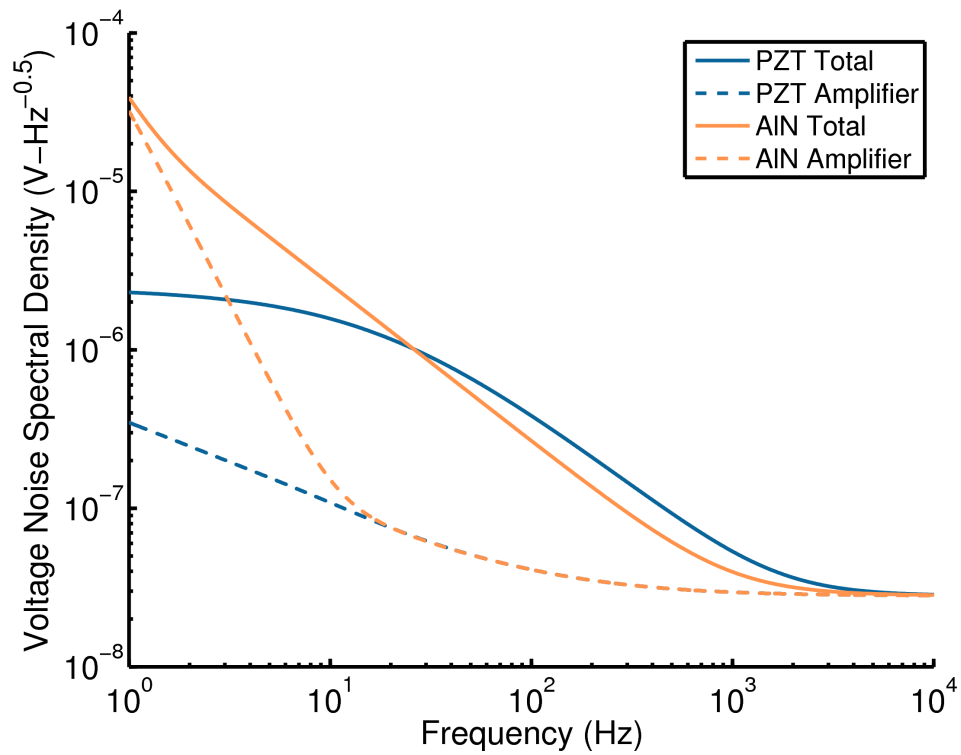


Examples from Univ. Neuchatel – Mars Phoenix Lander AFM and epitaxial PZT cantilever

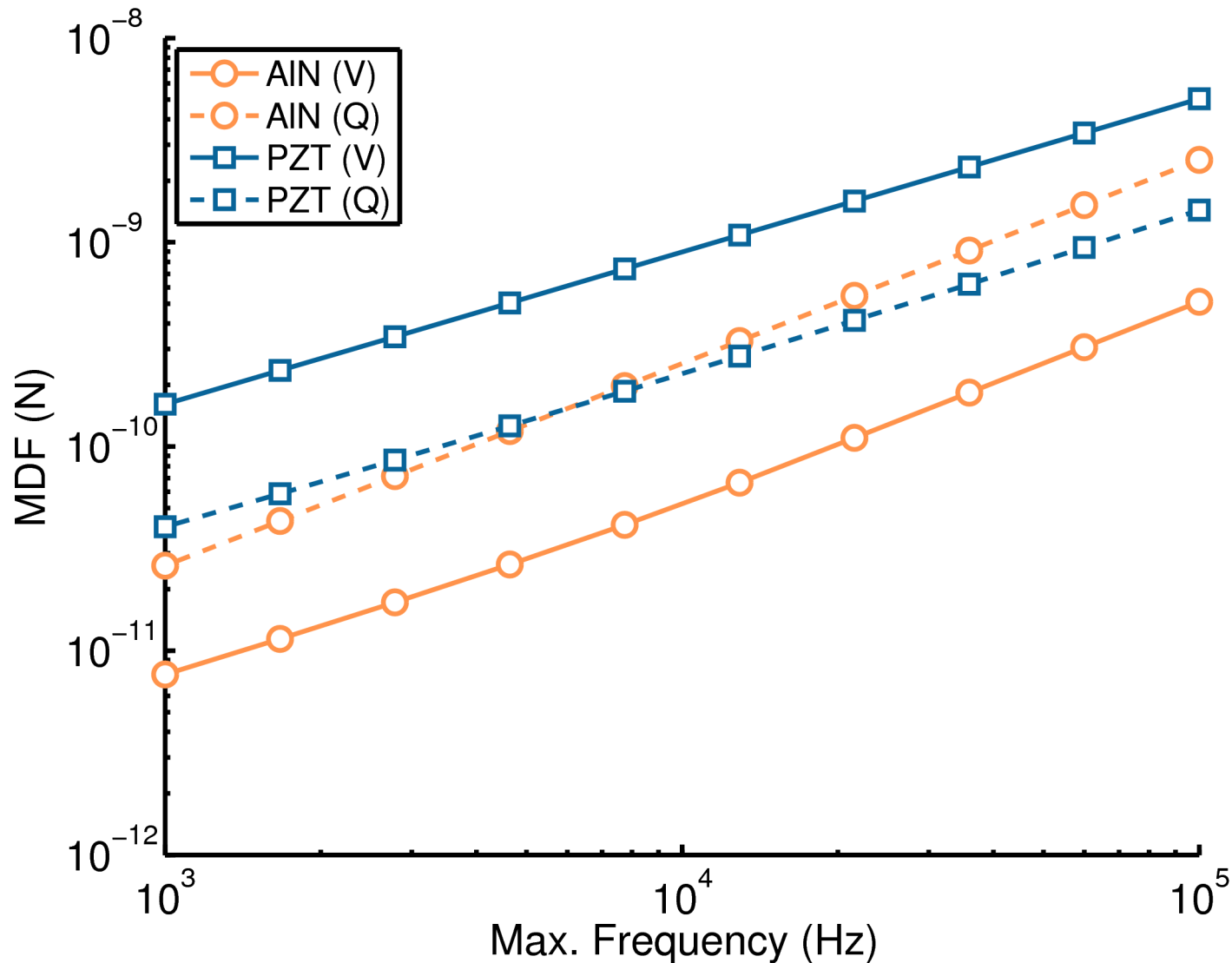
Comparing PR and PE Sensing



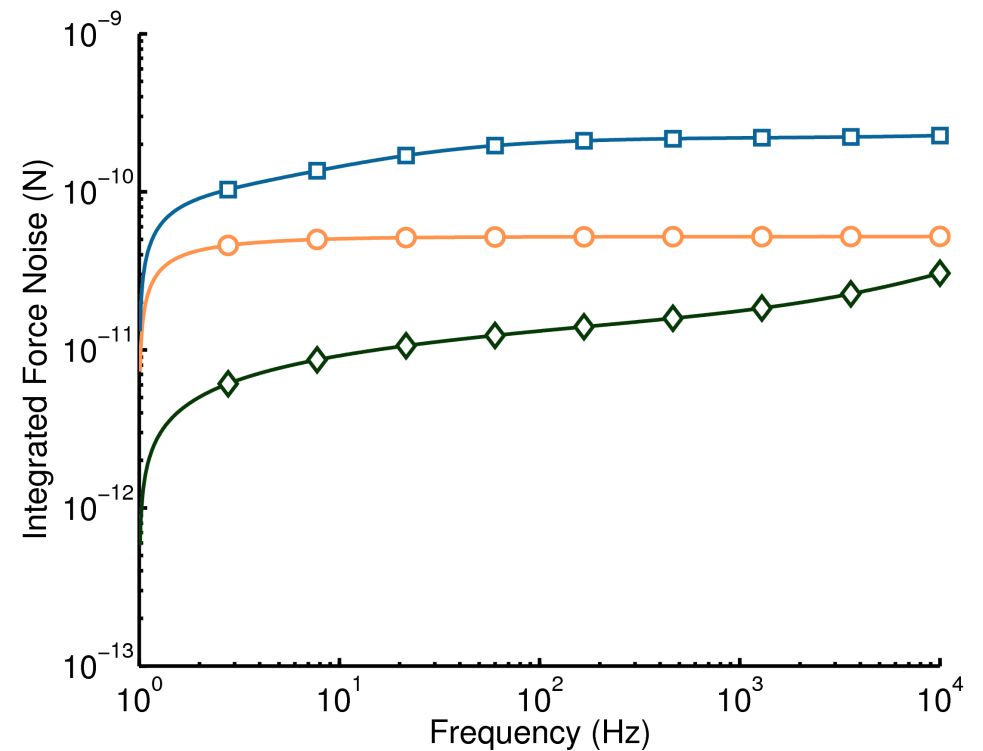
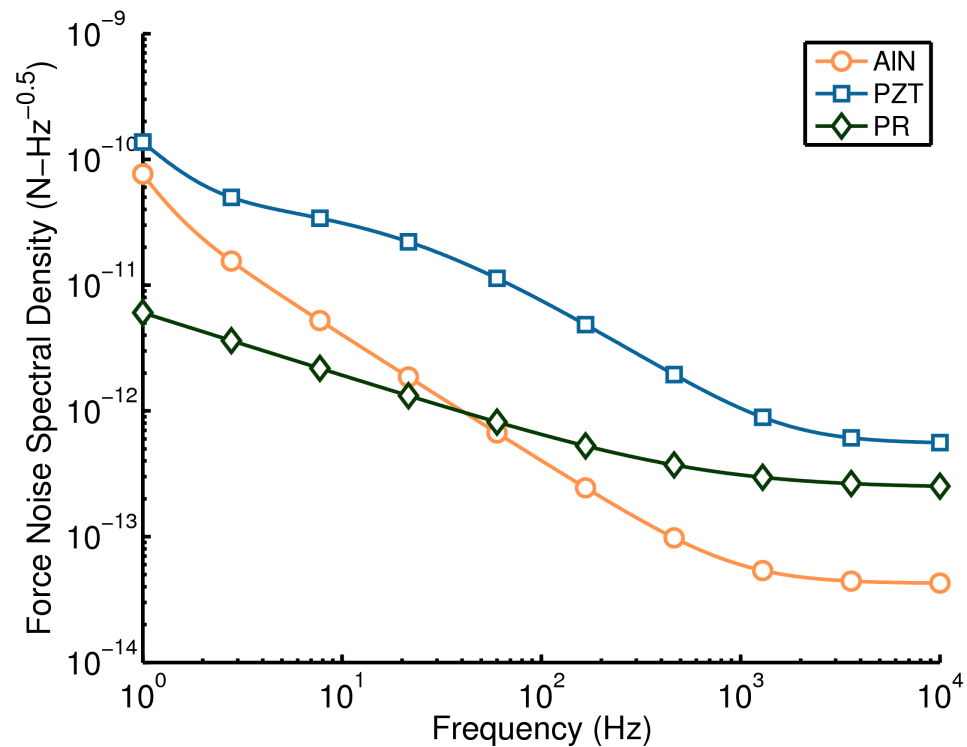
PE Noise



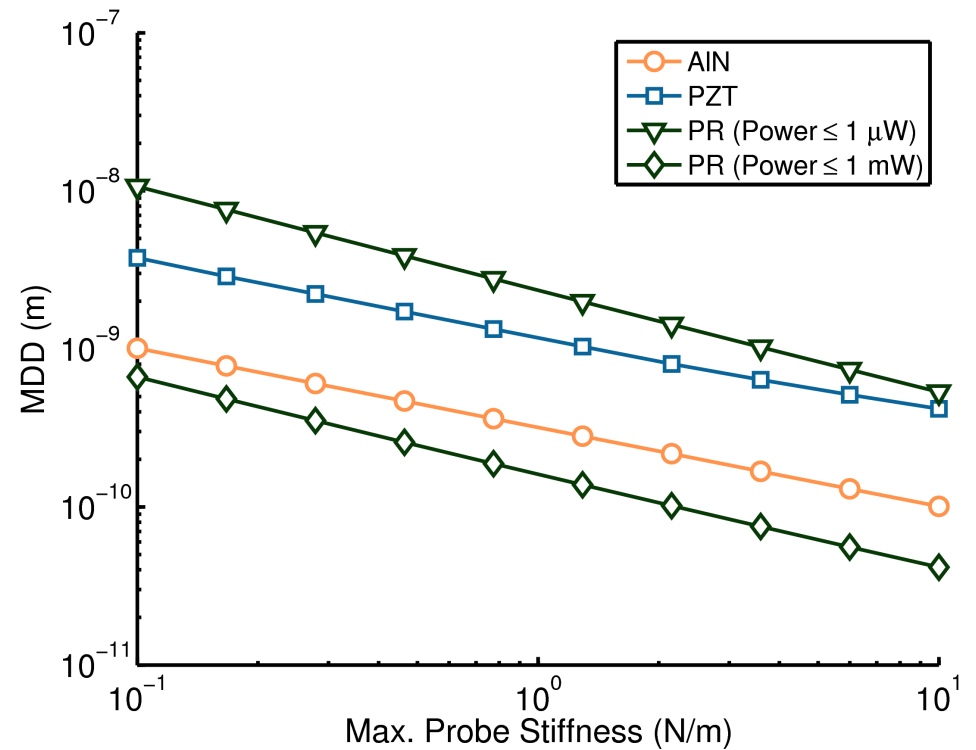
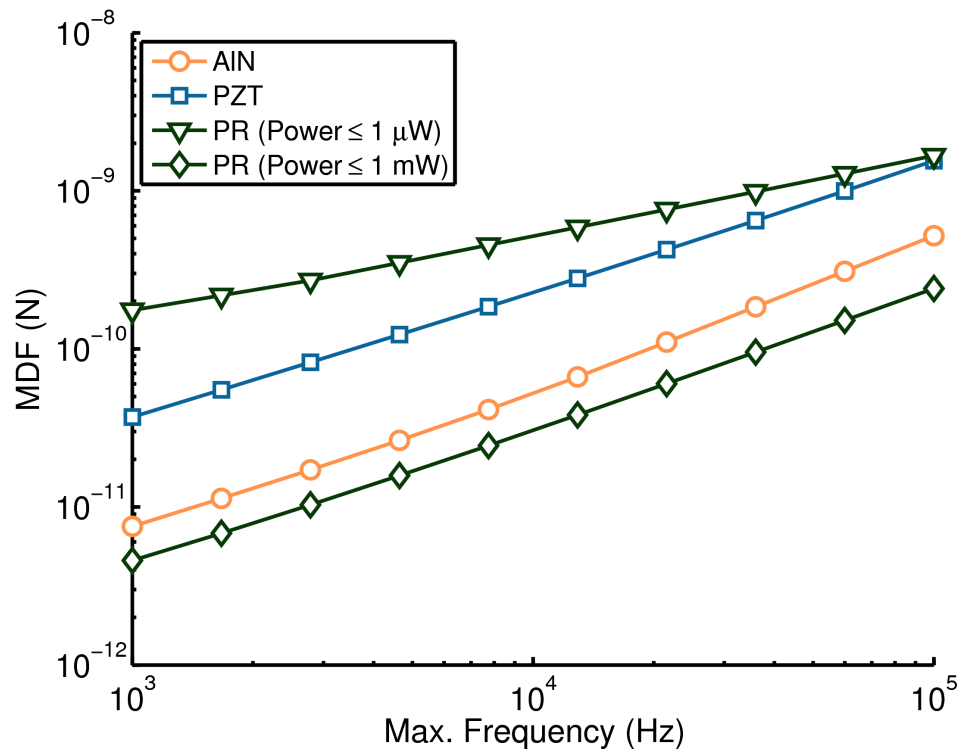
Comparison of PE Sensing Modes



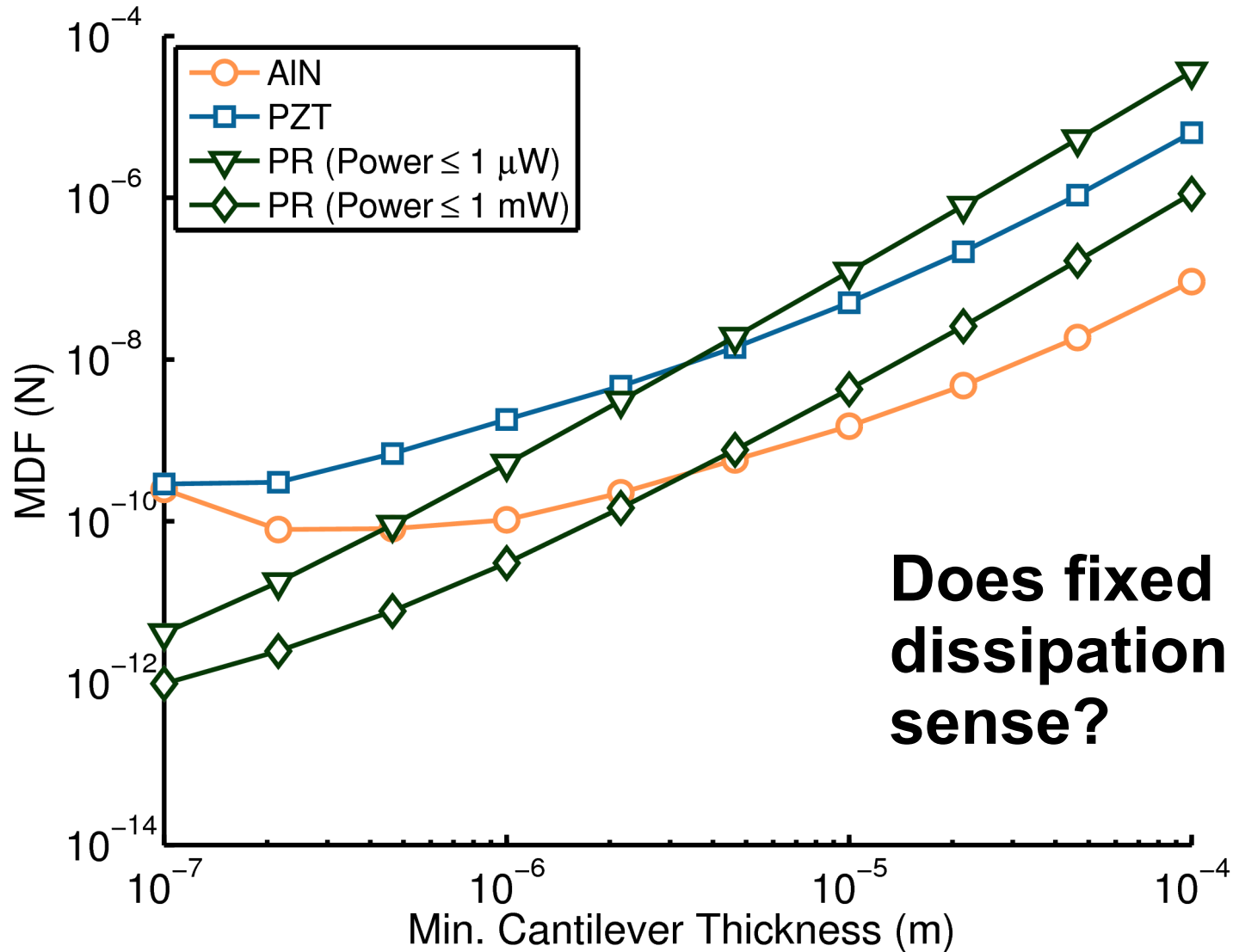
Detailed PR vs. PE Comparison



Force and Displacement Sensing

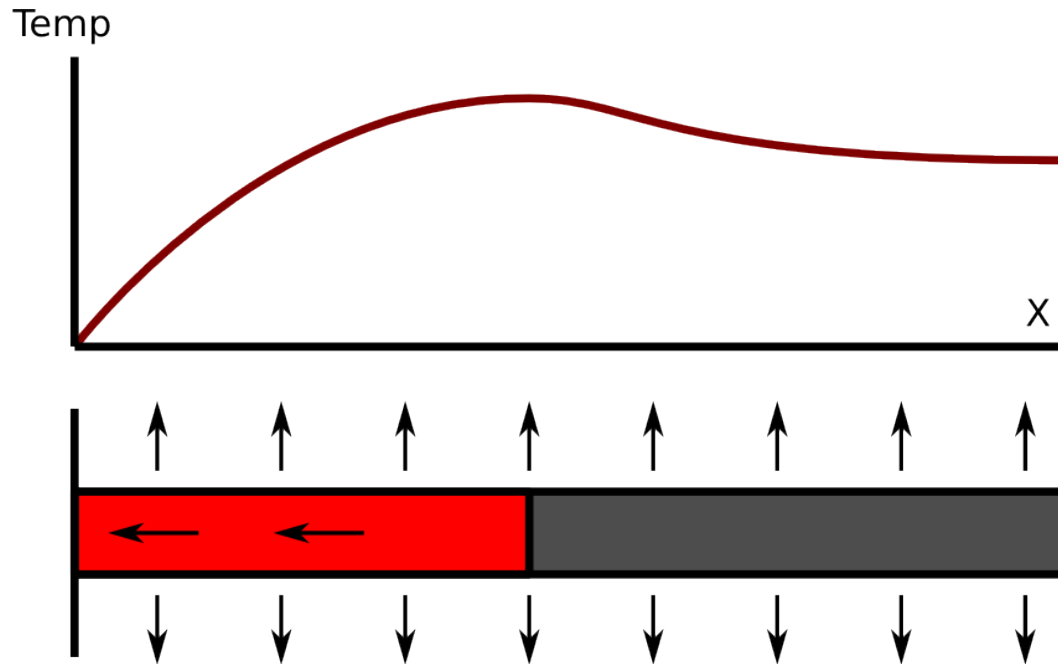


Thickness and Power



**Does fixed power
dissipation make
sense?**

Thermal Issues with Cantilever Design



B.C. Fixed Temp

Adiabatic

$$-kw_c t_c \frac{\partial^2 T(x)}{\partial x^2} + 2hw_c(T(x) - T_\infty) = Q(x)$$

$$Q(x) = W/l_{pr} \quad x \in [0, l_{pr}]$$

$k = 130 \text{ W/m-K}$

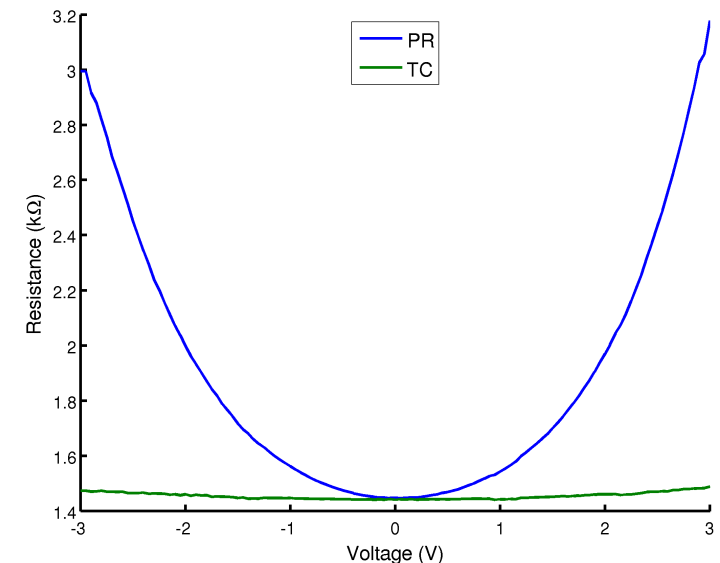
$h = 2000 \text{ W/m}^2\text{-K}$ (per K.J. Kim, W.P. King 2009)

Modeling

- Comsol
- 1D numerical

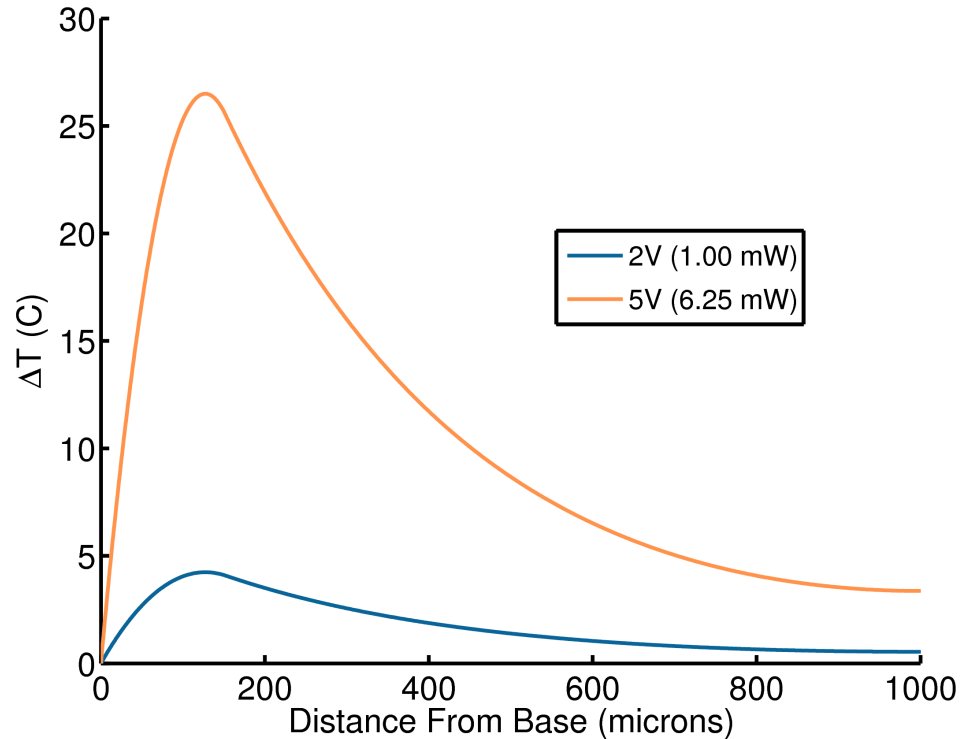
Measuring

- IR microscope
- Raman spectroscopy
- Resistance + temp calib.



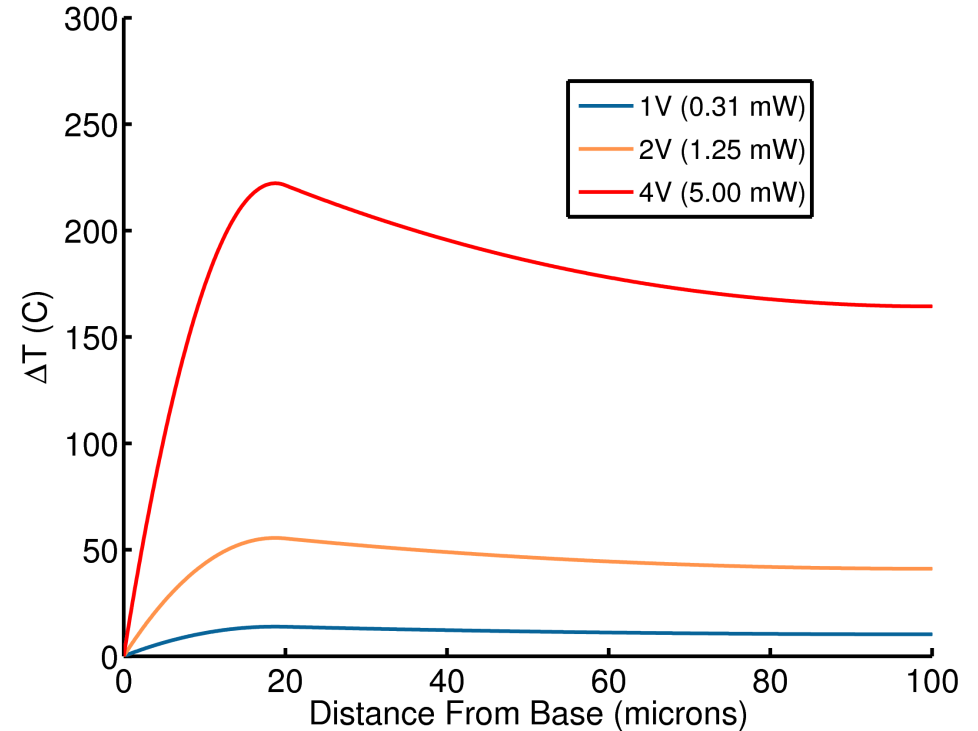
Comparing Cantilever Designs

Typical *C. elegans* Cantilevers



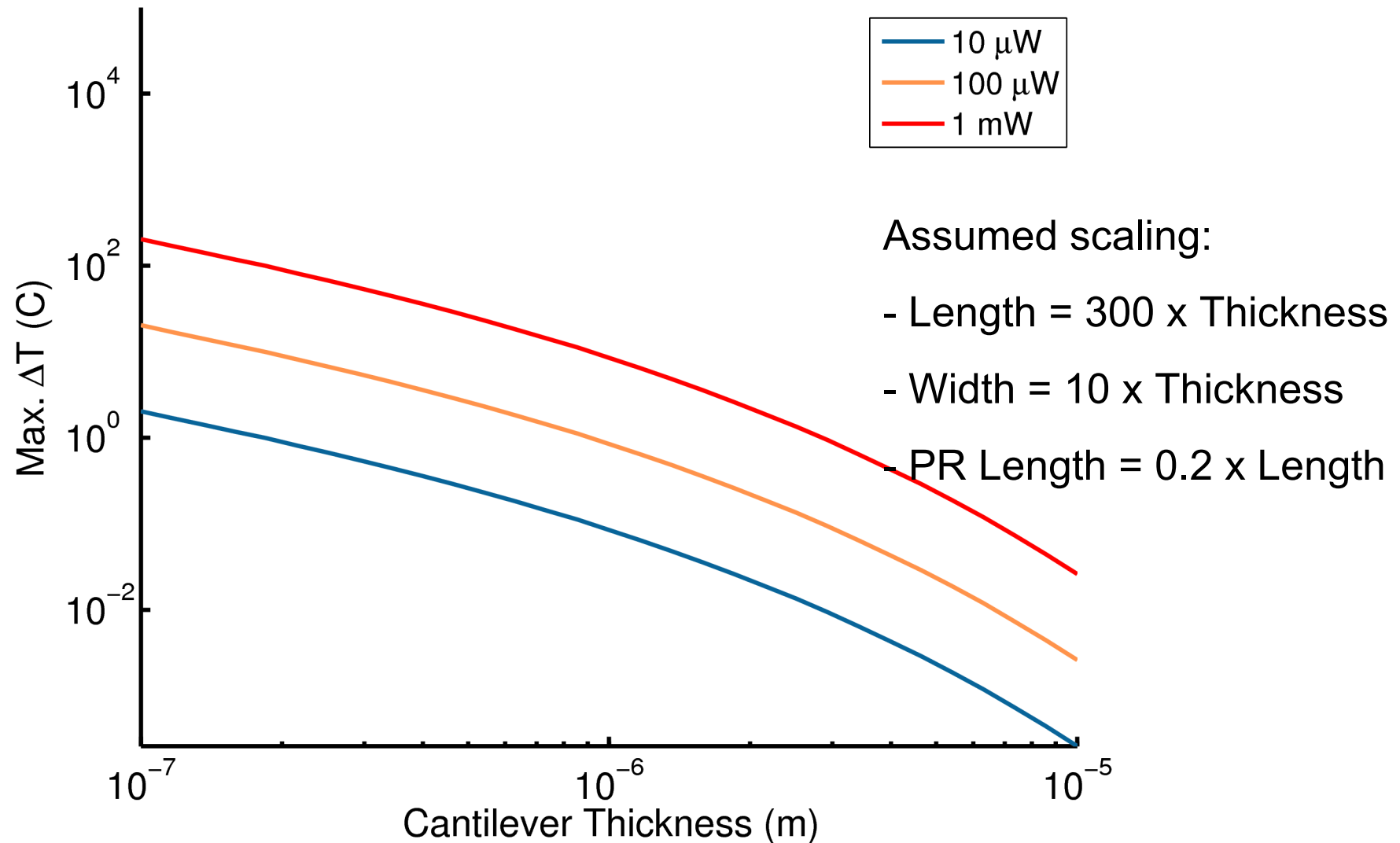
Cantilever = 1000 μm x 30 μm x 3 μm
PR = 153 μm long, 1 k Ω

Typical Cell/Molecule Cantilevers

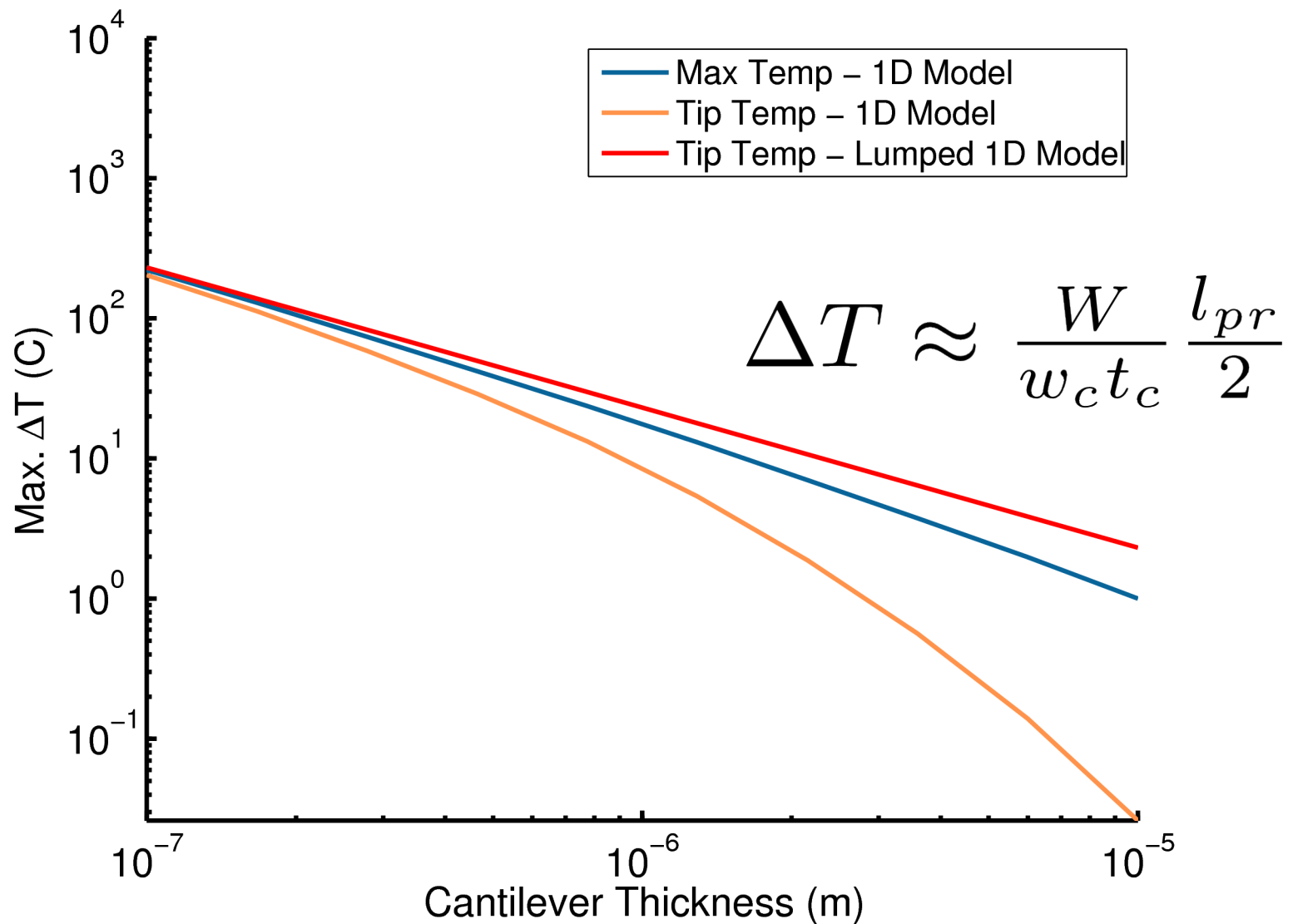


Cantilever = 100 μm x 5 μm x 300 nm
PR = 20 μm long, 2 k Ω

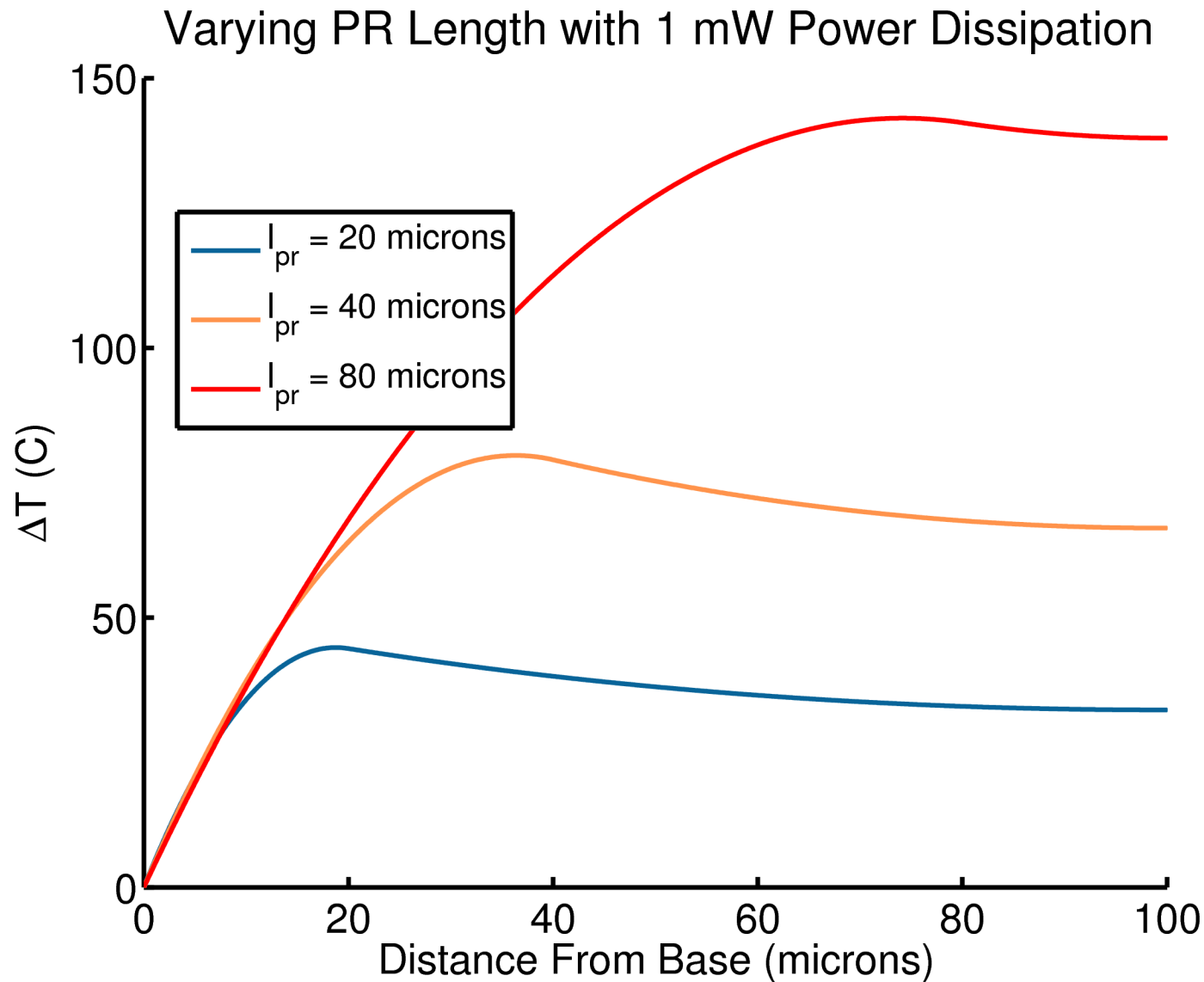
Temp. and Cantilever Size Scaling



Conduction vs. Convection



The Effect of PR Length



Tip Temp. vs Power Constraints

- Optimized for 1 Hz – 10 kHz ($f_0 = 20$ kHz)
- Cantilever = 135 μm x 2 μm x 300 nm

	Power < 1 mW	Power < 0.1 mW	Temp. < 10K
PR Length (μm)	40	18	10
Resistance (kOhm)	5.7	4.4	1.8
Bias (V)	4.8	1.3	1.1
Power (mW)	1	0.1	0.15
Tip Temp Rise (K)	<u>254</u>	<u>11.5</u>	<u>10</u>
MDF (pN)	<u>3.6</u>	<u>6.7</u>	<u>6.4</u>
MDD (nm)	5	9.3	8.8

Conclusions

- PR vs PE sensing
 - PR and PE resolution is limited by device (Johnson, Hooge) and amplifier noise
 - Use PR for thin cantilevers (< 1 micron), low frequencies (< 10 Hz) and moderate power dissipations (> 0.1 mW)
 - Use PE for thick cantilevers, maximizing sensitivity
- PR Thermal Design
 - Power dissipation needs to scale with device dimensions
 - Conduction dominates convection for small devices
 - Tip temp. can be minimized with a small impact on resolution